

3.2x2.4mm SMD CHIP LED LAMP

PRELIMINARY SPEC

Features

- 3.2x2.4mm SMT LED, 2.4mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 1500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

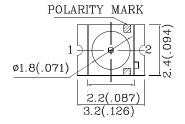


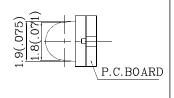


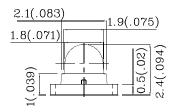
Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

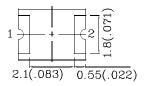
Absolute Maximum Ratings (TA=25°C)		M2ACY (AlInGaP)	Unit
Reverse Voltage	$V_{\rm R}$	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation	Рт	75	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	-0











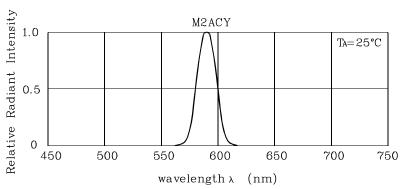
Operating Characteristics (TA=25°C)		M2ACY (AlInGaP)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	2.0	V
Forward Voltage (Max.) (IF=20mA)	VF	2.5	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	590	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	589	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	20	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	45	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZM2ACY78W	Yellow	AlInGaP	Water Clear	900	2490	590	20°
Published Date : JA	N 12,2009	Drawing No :	XDSB2804	V1	Checked : F	B.L.LIU	P.1/4



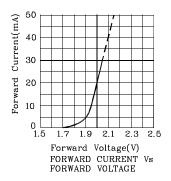
3.2x2.4mm SMD CHIP LED LAMP

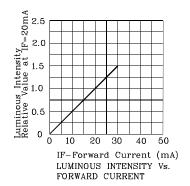


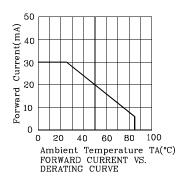


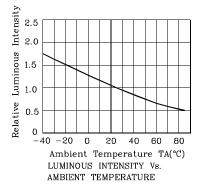
RELATIVE INTENSITY Vs. WAVELENGTH

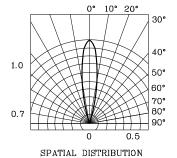
❖ M2ACY









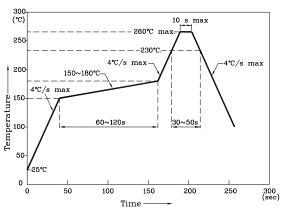


Published Date : JAN 12,2009 Drawing No : XDSB2804 V1 Checked : B.L.LIU P.2/4

3.2x2.4mm SMD CHIP LED LAMP

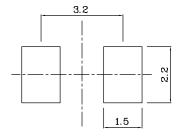
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

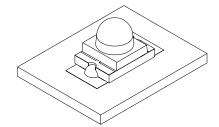
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

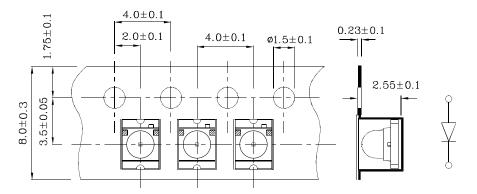
- 1. Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: $145^{\circ}c-260^{\circ}c$.
- Do not put stress to the epoxy resin during high temperatures conditions.
- **❖** Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)
- ❖ The device has a single mounting surface. The device must be mounted according to the specifications.





❖ Tape Specification (Units: mm)

TAPE



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

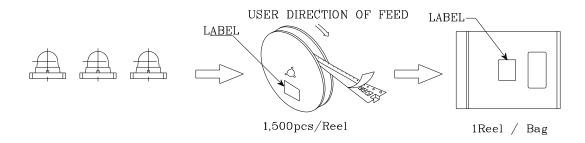
Note: Accuracy may depend on the sorting parameters.

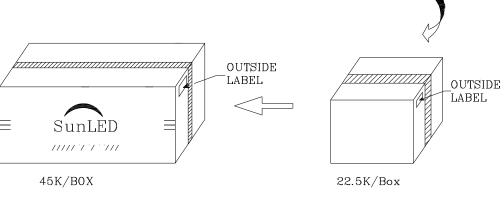


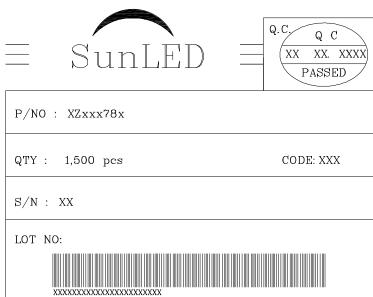
3.2x2.4mm SMD CHIP LED LAMP

PACKING & LABEL SPECIFICATIONS

XZM2ACY78W







RoHS Compliant

Published Date : JAN 12,2009 Drawing No : XDSB2804 V1 Checked : B.L.LIU P.4/4